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(54) Title: CHEMICAL PLANARIZATION OF NON-METALLIC MATERIALS

(57) Abstract: A pad for performing abrasive-free chemical pla-
narization of a substrate comprises a polymer layer configured to
contact the substrate during the abrasive-free chemical planarization.
The polymer layer comprises a cerium species.

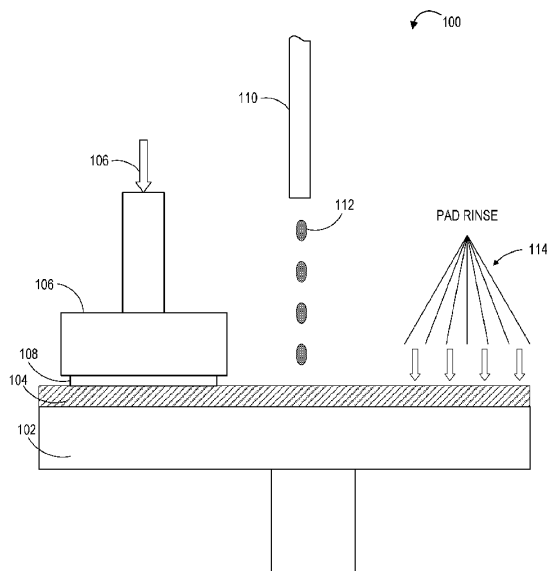


FIG. 1

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